In the Claims:

This listing of claims replaces all prior versions, and listings, of claims in the application.

1. (Currently Amended) A polyimide film obtainable by reacting an aromatic diamine having a benzoxazole structure with an aromatic tetracarbonic acid anhydride, which film has a planar orientation coefficient of 0.79-0.89 as measured by [[the]] an X-ray diffraction method[[,]] and a dielectric constant of 2.7-3.1 at 100 GHz as measured by a cavity resonance perturbation method.

2. (Original) The polyimide film of claim 1, having a dielectric loss tangent at 100 GHz of 0.0001-0.03 as measured by the cavity resonance perturbation method.

3. (Currently Amended) The polyimide film of claim 1 [[or 2]], having dielectric constants of 2.7-3.1 at 1 GHz and 2.6-3.0 at 100 GHz, as measured by the cavity resonance perturbation method.

4. (Currently Amended) The polyimide film of ~~any of claims 1 to 3~~ claim 1, which has a density of 1.47 g/cm^3 - 1.55 g/cm^3.

5. (Currently Amended) A polyimide film obtainable by reacting an aromatic diamine having a benzoxazole structure with an aromatic tetracarbonic acid anhydride, wherein the amount of water vaporized at a high temperature during heating at 500°C for 10 sec of the film immediately after helium purge at 170°C for 7 min and preliminary drying is not more than 5000 ppm.

6. (Currently Amended) The polyimide film of ~~any of claims 1 to 5~~ claim 1, wherein the ratio ($\varepsilon_{65}/\varepsilon_D$) of the dielectric constant ε_{65} at 100 GHz of the film humidity-conditioned under [[the]] a constant temperature and humidity conditions of 20°C, 65% RH for 94 hr, as measured by [[a]] the cavity resonance perturbation method, to the dielectric constant εD at 100 GHz of the film vacuum dried under the conditions of 120°C, for 24 hr, as measured by [[a]] the cavity resonance perturbation method, is within the range of 1.00-1.10.

7. (Currently Amended) A polyimide film obtainable by reacting an aromatic diamine having a benzoxazole structure with an aromatic tetracarbonic acid anhydride, wherein the absolute value of the difference between [[the]] a surface planar orientation degree of one surface (surface A) and [[the]] a surface planar orientation degree of the other surface (surface B) of the film is 0-2.

8. (Currently Amended) The polyimide film of ~~any of claims 1 to~~ claim 7, wherein the surface planar orientation degree of [[a]] the film surface having a higher surface planar orientation degree is not more than 15.

9. (Currently Amended) The polyimide film of ~~any of claims 1 to 8~~ claim 7, which has a curling degree of 0%-5%.

10. (Canceled)

11. (Currently Amended) A base substrate for printed wiring assemblies, which comprises the polyimide film of ~~any of claims~~ claim 1 ~~to 10~~.

12. (Currently Amended) A method of producing a polyimide film, which comprises reacting an aromatic diamine with an aromatic tetracarbonic acid anhydride to give a polyamide acid, casting a solution thereof on a support and drying the solution ~~and the like~~ to give a self-supporting polyimide precursor film ~~(green film)~~ and polyimidating said precursor film, wherein the polyimide precursor film ~~(green film)~~ satisfies [[all]] the relationships shown by the following formulas between an imidation rate Aim of one surface side (surface A side) and an imidation rate Bim of the other surface side (surface B side) of the polyimide precursor film ~~(green film)~~ and said polyimide precursor film is subjected to imidation[[.]]:

formula 1[[;]]: $|Aim-Bim| \leq 5$

formula 2[[;]]: $0 \leq Aim \leq 15$

formula 3[[;]]: $0 \leq Bim \leq 15$.

13. (New) The polyimide film of claim 2, having dielectric constants of 2.7-3.1 at 1 GHz and 2.6-3.0 at 100 GHz, as measured by the cavity resonance perturbation method.

14. (New) The polyimide film of claim 2, which has a density of 1.47 g/cm^3 - 1.55 g/cm^3.

15. (New) The polyimide film of claim 7, wherein the ratio ($\varepsilon_{65}/\varepsilon_D$) of the dielectric constant ε_{65} at 100 GHz of the film humidity-conditioned under a constant temperature and humidity conditions of 20°C, 65% RH for 94 hr, as measured by the cavity resonance perturbation method, to the dielectric constant εD at 100 GHz of the film vacuum dried under the conditions of 120°C, for 24 hr, as measured by the cavity resonance perturbation method, is within the range of 1.00-1.10.

16. (New) The polyimide film of claim 8, which has a curling degree of 0%-5%.

17. (New) A base substrate for printed wiring assemblies, which comprises the polyimide film of claim 4.

18. (New) A base substrate for printed wiring assemblies, which comprises the polyimide film of claim 5.

19. (New) A base substrate for printed wiring assemblies, which comprises the polyimide film of claim 7.